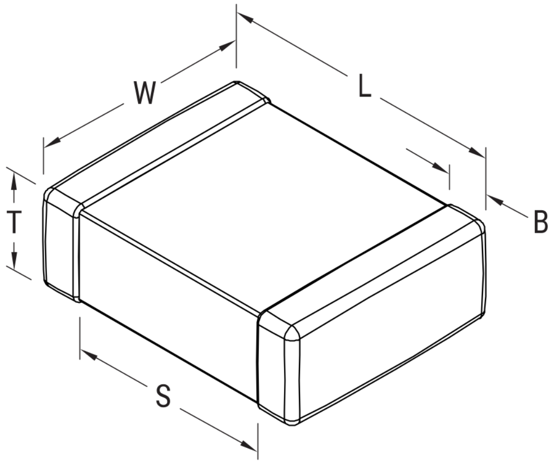
C0805C102M3GEC7210

ESD SMD Comm C0G, Ceramic, 1000 pF, 20%, 25 VDC, C0G, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805



Click here for the 3D model.

General Information

Series	ESD SMD Comm C0G
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	13 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	0.9mm +/-0.10mm
S	0.75mm MIN
B	0.5mm +/-0.25mm

Specifications

Capacitance	1000 pF
Measurement Condition	1 MHz 1.0Vrms
Capacitance Tolerance	20%
Voltage DC	25 VDC
ESD Level per AEC-Q200	8,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	C0G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Packaging Specifications

Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

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